

DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

☐ Original ☐ Supplemental ☐ Substitute ☒ PCT ☐ DESIGN

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: METHOD FOR MANUFACTURING SEMICONDUCTOR CHIP

of which is described and claimed in:

☐ the attached specification, or

☐ the specification in application Serial No. _____, filed _____, and with amendments through _____, or

☒ the specification in International Application No. PCT/JP2004/017955, filed December 2, 2004, and as amended on _____ (if applicable).

I hereby state that I have reviewed and understand the content of the above-identified specification, including the claims, as amended by any amendment(s) referred to above.

I acknowledge my duty to disclose to the Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim priority benefits under Title 35, United States Code, §119 (and §172 if this application is for a Design) of any application(s) for patent or inventor's certificate listed below and have also identified below any application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

| COUNTRY | APPLICATION NO. | DATE OF FILING | PRIORITY CLAIMED |
|---------|-----------------|--------------------|------------------|
| Japan | 2003-403431 | December 2, 2003 | YES |
| Japan | 2004-107584 | March 31, 2004 | YES |
| Japan | 2004-282807 | September 28, 2004 | YES |
| Japan | 2004-282808 | September 28, 2004 | YES |

I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

| APPLICATION SERIAL NO. | U.S. FILING DATE | STATUS: PATENTED, PENDING, ABANDONED |
|------------------------|------------------|--------------------------------------|
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And I hereby appoint Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Warren M. Cheek, Jr., Reg. No. 33,367; Nils Pedersen, Reg. No. 33,145; Charles R. Watts, Reg. No. 33,142; Michael S. Huppert, Reg. No. 40,268; Jeffrey R. Filipek, Reg. No. 41,471; and Douglas W. Hahm, Reg. No. 44,142, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., as well as any other attorneys and agents associated with Customer No. 000513, to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys and agents named herein to accept and follow instructions from YASUTOMI & ASSOCIATES as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

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| Direct Correspondence to: <p style="text-align: center;">CUSTOMER NO. 000513</p> | Direct Telephone Calls to: <p style="text-align: center;">WENDEROTH, LIND & PONACK, L.L.P. 2033 "K" Street, N.W., Suite 800 Washington, D.C. 20006-1021</p> <p style="text-align: center;">Phone: (202) 721-8200 Fax: (202) 721-8250</p> |
|--|---|

| | | | |
|-----------------------------|---|----------------------------|---------------------------------|
| Full Name of First Inventor | FAMILY NAME SUGITA | FIRST GIVEN NAME Daihei | SECOND GIVEN NAME |
| Residence & Citizenship | CITY Saitama, | STATE OR COUNTRY Japan | COUNTRY OF CITIZENSHIP Japan |
| Post Office Address | ADDRESS CITY STATE OR COUNTRY ZIP CODE c/o Sekisui Chemical Co., Ltd., 3535, Kurohama, Hasuda-shi, Saitama 349-0198 Japan | | |

| | | | |
|------------------------------|--|------------------------------|------------------------|
| Full Name of Second Inventor | FAMILY NAME FUKUOKA | FIRST GIVEN NAME Masateru | SECOND GIVEN NAME |
| Residence & Citizenship | CITY Osaka, | STATE OR COUNTRY Japan | COUNTRY OF CITIZENSHIP |
| Post Office Address | ADDRESS CITY STATE OR COUNTRY ZIP CODE c/o Sekisui Chemical Co., Ltd., 2-1, Hyakuyama, Shimamotocho, Mishima-gun, Osaka 618-8589 Japan | | |

| | | | |
|-----------------------------|--|------------------------------|---------------------------------|
| Full Name of Third Inventor | FAMILY NAME HATAI | FIRST GIVEN NAME Munehiro | SECOND GIVEN NAME |
| Residence & Citizenship | CITY Osaka, | STATE OR COUNTRY Japan | COUNTRY OF CITIZENSHIP Japan |
| Post Office Address | ADDRESS CITY STATE OR COUNTRY ZIP CODE c/o Sekisui Chemical Co., Ltd., 2-1, Hyakuyama, Shimamotocho, Mishima-gun, Osaka 618-8589 Japan | | |

| | | | |
|------------------------------|--|-----------------------------|---------------------------------|
| Full Name of Fourth Inventor | FAMILY NAME HAYASHI | FIRST GIVEN NAME Satoshi | SECOND GIVEN NAME |
| Residence & Citizenship | CITY Osaka, | STATE OR COUNTRY Japan | COUNTRY OF CITIZENSHIP Japan |
| Post Office Address | ADDRESS CITY STATE OR COUNTRY ZIP CODE c/o Sekisui Chemical Co., Ltd., 2-1, Hyakuyama, Shimamotocho, Mishima-gun, Osaka 618-8589 Japan | | |

| | | | |
|------------------------------------|--|-------------------------------------|--|
| Full Name of Fifth Inventor | FAMILY NAME SHIMOMURA | FIRST GIVEN NAME Kazuhiro | SECOND GIVEN NAME |
| Residence & Citizenship | CITY Saitama, | STATE OR COUNTRY Japan | COUNTRY OF CITIZENSHIP Japan |
| Post Office Address | ADDRESS c/o Sekisui Chemical Co., Ltd., 3535, Kurohama, Hasuda-shi, Saitama | CITY 349-0198 | STATE OR COUNTRY Japan |

| | | | |
|------------------------------------|--|--------------------------------------|--|
| Full Name of Sixth Inventor | FAMILY NAME KITAJIMA | FIRST GIVEN NAME Yoshikazu | SECOND GIVEN NAME |
| Residence & Citizenship | CITY Saitama, | STATE OR COUNTRY Japan | COUNTRY OF CITIZENSHIP Japan |
| Post Office Address | ADDRESS c/o Sekisui Chemical Co., Ltd., 3535, Kurohama, Hasuda-shi, Saitama | CITY 349-0198 | STATE OR COUNTRY Japan |

| | | | |
|--------------------------------------|--|-------------------------------------|--|
| Full Name of Seventh Inventor | FAMILY NAME OYAMA | FIRST GIVEN NAME Yasuhiko | SECOND GIVEN NAME |
| Residence & Citizenship | CITY Tokyo, | STATE OR COUNTRY Japan | COUNTRY OF CITIZENSHIP Japan |
| Post Office Address | ADDRESS c/o Sekisui Chemical Co., Ltd., 3-17, Toranomom 2-chome, Minato-ku, Tokyo | CITY 105-8450 | STATE OR COUNTRY Japan |

I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1st Inventor _____ Date _____
Daihei SUGITA

2nd Inventor _____ Date _____
Masateru FUKUOKA

3rd Inventor _____ Date _____
Munehiro HATAI

4th Inventor _____ Date _____
Satoshi HAYASHI

5th Inventor _____ Date _____
Kazuhiro SHIMOMURA

6th Inventor _____ Date _____
Yoshikazu KITAJIMA

7th Inventor _____ Date _____
Yasuhiko OYAMA

The above application may be more particularly identified as follows:

U.S. Application Serial No. _____ Filing Date April 27, 2006

Applicant Reference Number SK326US Atty Docket No. 2006 0490A

Title of Invention METHOD FOR MANUFACTURING SEMICONDUCTOR CHIP